

Title of Change:	Erratum to FPCN25897X to Include Internal Leadframe Design Change for FOD2712A, FOD2712AR2, FOD2712AR2V, and FOD2712AV
Effective date:	11 Aug 2026
Contact information:	Contact your local onsemi Sales Office
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Wafer Fab Change, Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
None	

Description and Purpose:

This notification serves as an erratum to FPCN25897X, originally issued on 24 October 2024, to include internal leadframe design change.

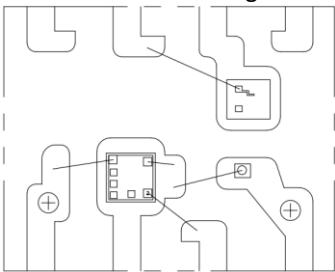
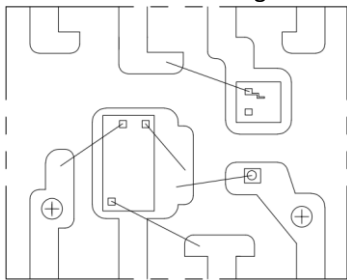
Specifically, the Die Attach Paddle (DAP) size has been increased to better accommodate the alternate die source identified under Change Item 2 of FPCN25897X. This additional change impacts only the following products:

- FOD2712A
- FOD2712AR2
- FOD2712AR2V
- FOD2712AV

The qualification for FPCN25897X was conducted using material that already incorporated this leadframe design change.

Therefore, no additional qualification is required as this change was already covered under the original qualification and sample evaluation.

Change summary:

Item	Current	After Change
1	Internal DAP design: 	Internal DAP design: 

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

FOD2712A	FOD2712AR2	FOD2712AR2V
FOD2712AV		